

NOTES:

1. PLACE ALL PARTS ON A 0, 45, OR 90 DEGREE ORIENTATION.
2. DIFFERENTIAL NETS ARE: TDP/N, TDP\_DINP/N, MODP/N, TD\_DATA\_P/N, RDP/N, RD\_DINP/N, RD\_DATAP/N
3. DIFFERENTIAL DATA SHOULD BE ROUTED AS 100 OHM TRANSMISSION LINES ON OUTSIDE LAYERS UNLESS SPECIFIED
4. MODP/N AND TD\_DATA\_P/N SHOULD BE ROUTED AS 25 OHM TRANSMISSION LINE ON OUTSIDE LAYERS
5. DIFFERENTIAL NETS MUST MATCH WITHIN +/- 0.5 MILS
6. USE FR4-370 MATERIAL FOR ALL LAYERS.
7. STACKUP SHOULD BE TOP SIGNAL, L2 GND, L3 PWR, BOTTOM SIGNAL

REVISIONS

ECR	ECR NUMBER	DATE
	-----	xx/xx/xx

## SCHEMATIC SHEET INDEX:

- SHEET 01: COVER SHEET AND NOTES  
 SHEET 02: SCHEMATIC



### TEXAS INSTRUMENTS

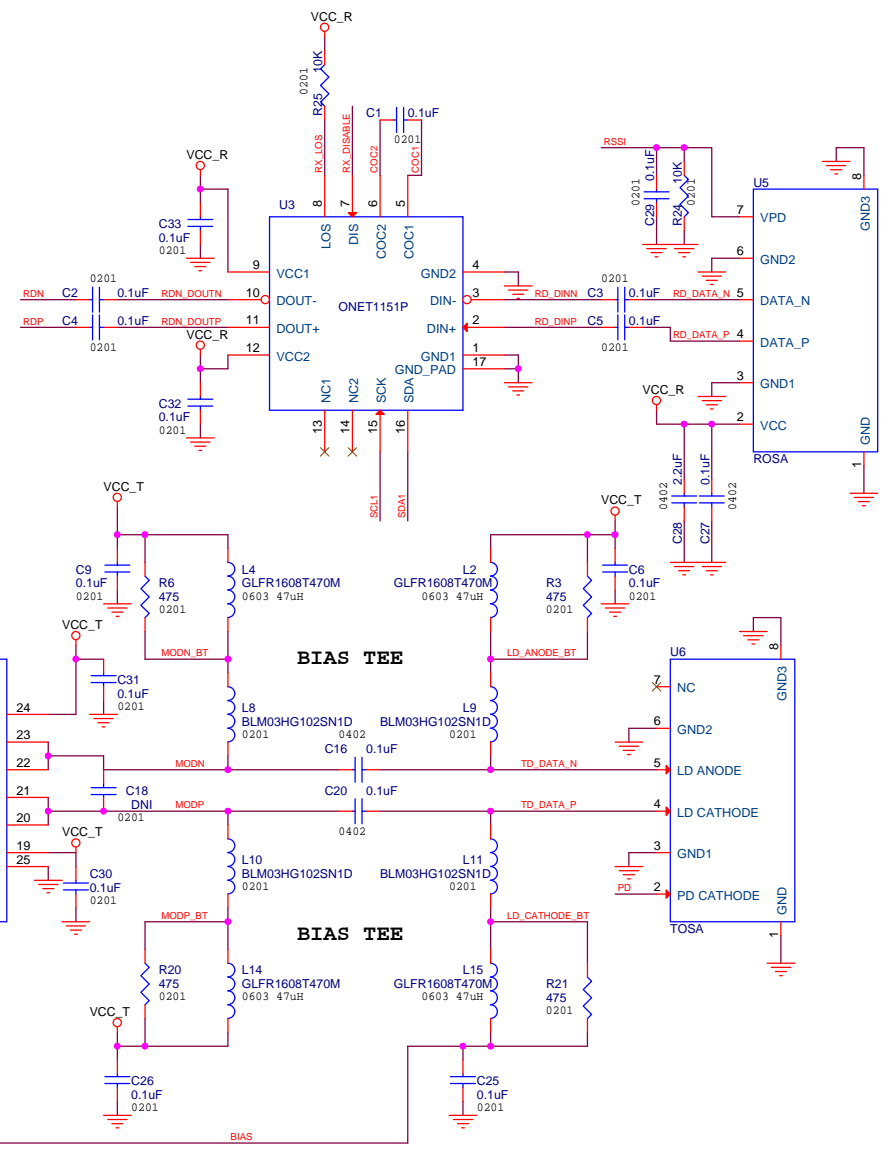
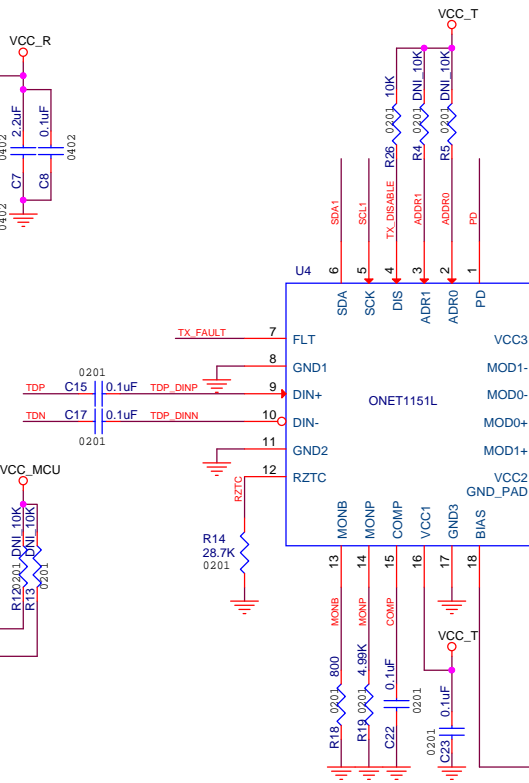
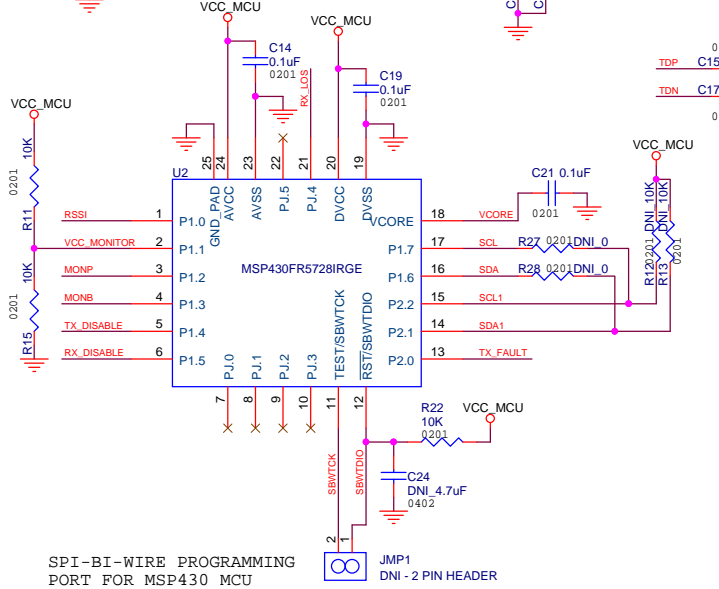
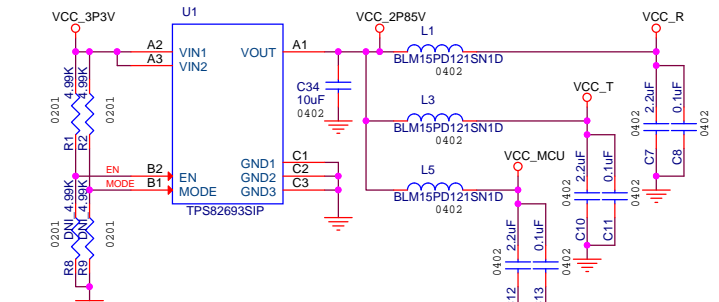
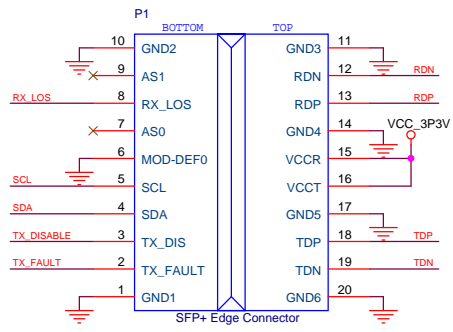
**SCHEMATIC TITLE**  
 ONET1151P/L 10G SFP+  
 REFERENCE DESIGN

<b>ENGINEER</b>	<b>DATE</b>
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<b>LAYOUT</b>	<b>DATE</b>
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**PAGE TITLE**  
 COVER PAGE AND NOTES

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B	6572665	NA	1 of 2

DATA SHEET REVISION: x.x.x  
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PAGE TITLE			
ONET1151P/L 10G SFP+ REFERENCE DESIGN			
SIZE	DOCUMENT NUMBER	REV	PAGE
B	6572665	NA	2 of 2

SPI-BI-WIRE PROGRAMMING PORT FOR MSP430 MCU

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